

F

E

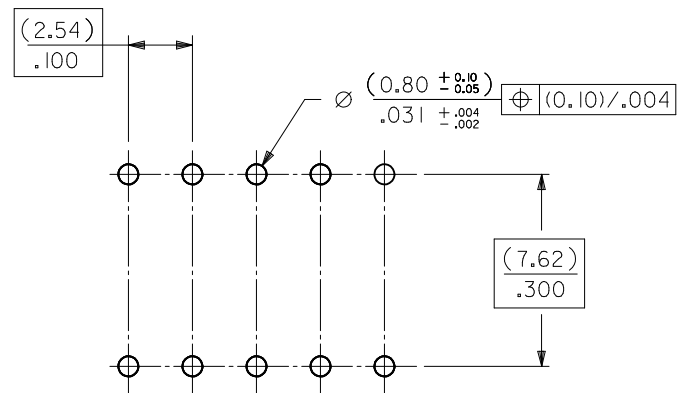
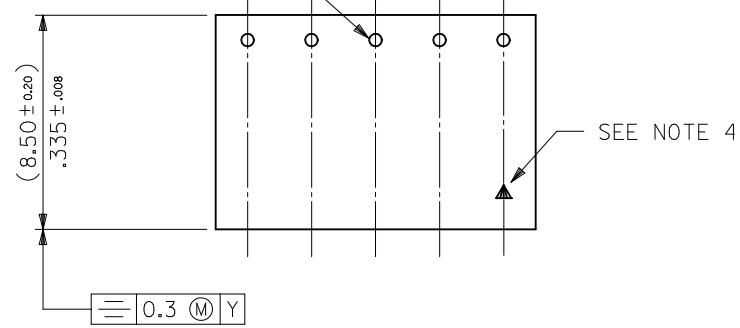
D

C

B

A

TERMINAL RETENTION FEATURE

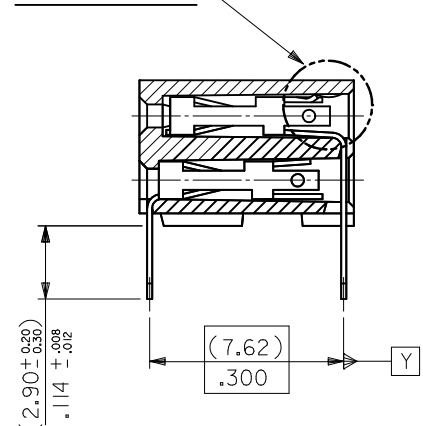


RECOMMENDED P.C. BOARD
HOLE PATTERN

NOTES

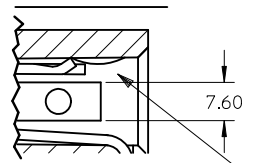
- 1) CONTACT-PLATED PHOSPHOR BRONZE.
- 2) HOUSING-15% GLASS FILLED POLYESTER. COLOUR-BLACK.
- 3) COMPATABLE WITH PCB HOLE PATTERN.
- 4) THIS MARK INDICATES CIRCUIT NO.1.
- 5) FOR (0.635)/.025 SQ. MALE PINS THE LENGTH MUST BE (5.65)/.222 MIN & (7.00)/.276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.
- 6) PRODUCT SPECIFICATION: PS-99020-0001
- 7) RECOMMENDED PCB THICKNESS 1.6MM

SEE DETAIL "A"



SECTION C-C

DETAIL "A"



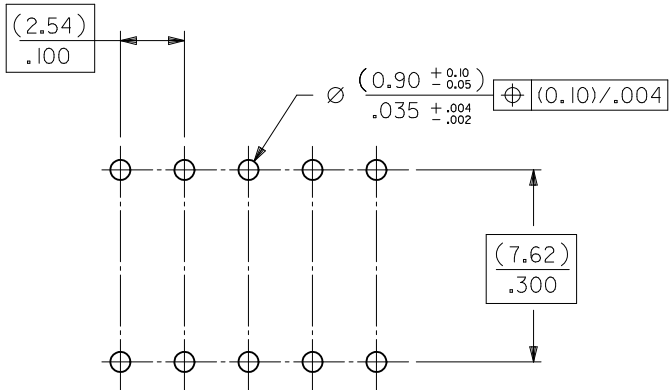
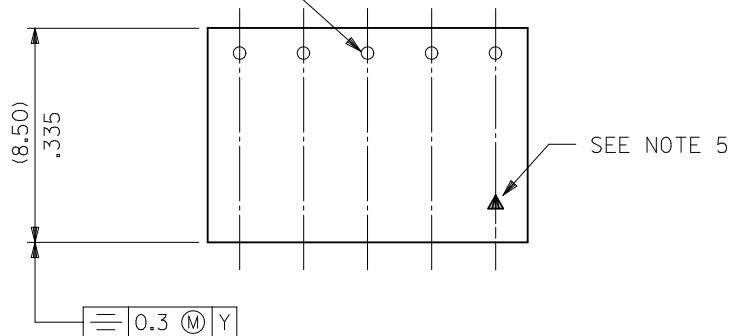
TERMINAL RETENTION FEATURE

SHT385, UPDATE SEC C-C- EC NO: S2011-1033 DRAWN:ATSEE 2011/06/06 CHKD:SKANG 2011/06/21 APPR:MLONG 2011/06/21			DESCRIPTION REV	QUALITY SYMBOLS F_A=0 F_C=0 F_P=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
						mm	INCH	DRAWN BY DATE DB 1987/07/14		TITLE C-GRID PCB CONN DR HORZ					
					4 PLACES	± ---	± ---	CHECKED BY DATE DB 1987/07/14							
					3 PLACES	± ---	± ---	APPROVED BY DATE MLONG 2010/01/14		molex MOLEX INCORPORATED					
					2 PLACES	± 0.20	± .008								
					1 PLACE	± ---	± ---	MATERIAL NO. DOCUMENT NO. SDA-90152							
					ANGULAR ± 2 °										
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SHEET NO. 1 OF 5							
C						SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

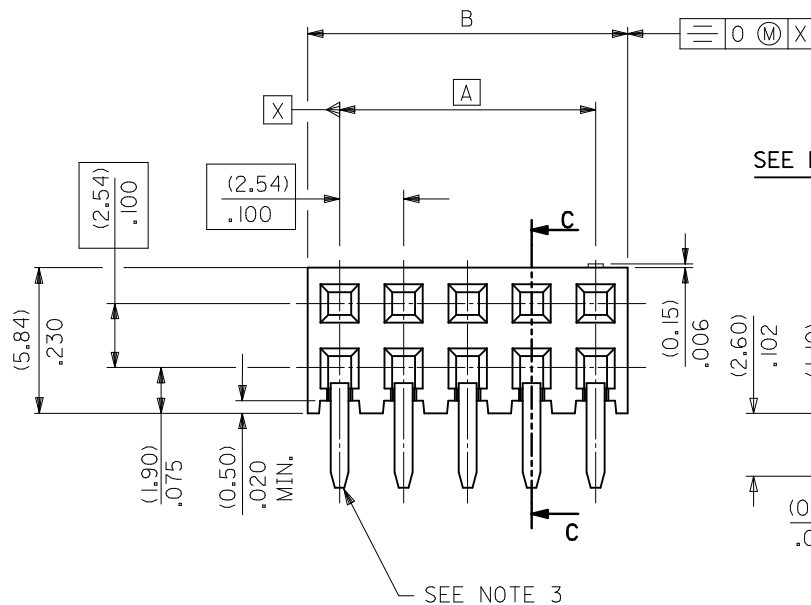
	10		9		8		7		6		5		4		3		2		1	
F	PART NO.	CKT	DIM. A		DIM. B (+0.00 -0.30 +0.00 -0.12)		PCS/ TUBE	PLATING VERSION A PRE-PLATED HOT DIP TIN 1.0 TO 2.5 microns (.00004" TO .00010").												F
	90152-XX04	4	(2.54) .100		(5.08) .200		109													
	06	6	(5.08) .200		(7.62) .300		73													
	08	8	(7.62) .300		(10.16) .400		55													
	10	10	(10.16) .400		(12.70) .500		44													
	12	12	(12.70) .500		(15.24) .600		36													
	14	14	(15.24) .600		(17.78) .700		31													
	16	16	(17.78) .700		(20.32) .800		27													
	18	18	(20.32) .800		(22.86) .900		24													
	20	20	(22.86) .900		(25.40) 1.000		22													
E	22	22					20	PLATING VERSION E 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												E
	24	24	(27.94) 1.100		(30.48) 1.200		18													
	26	26	(30.48) 1.200		(33.02) 1.300		16													
	28	28					14													
D	30	30	(35.56) 1.400		(38.10) 1.500		14	PLATING VERSION F 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												D
	32	32					13													
	34	34	(40.64) 1.600		(43.18) 1.700		12													
	36	36	(43.18) 1.700		(45.72) 1.800		12													
	38	38	(45.72) 1.800		(48.26) 1.900		11													
	40	40	(48.26) 1.900		(50.80) 2.000		11													
	42	42					10													
	44	44	(53.34) 2.100		(55.88) 2.200		10													
	46	46					10													
	48	48					9													
C	50	50	(60.96) 2.400		(63.50) 2.500		8	PLATING VERSION G 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												C
	52	52					8													
	54	54					8													
	56	56	(68.58) 2.700		(71.12) 2.800		7													
	58	58					7													
	60	60	(73.66) 2.900		(76.20) 3.000		7													
B	62	62					6	90152 - X X Y Y </												

10 9 8 7 6 5 4 3 2 1

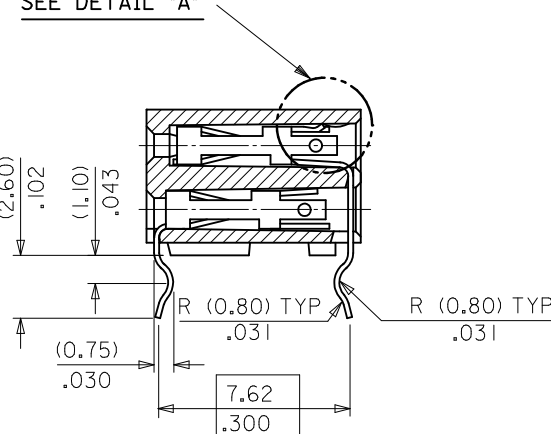
TERMINAL RETENTION FEATURE



RECOMMENDED P.C. BOARD
HOLE PATTERN



SEE DETAIL "A"

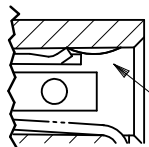


SECTION C-C

NOTES

- 1) CONTACT-PLATED PHOSPHOR BRONZE.
- 2) HOUSING-15% GLASS FILLED POLYESTER. COLOUR-BLACK.
- 3) COMPATABLE WITH PCB HOLE PATTERN.
- 4) RECOMMENDED PC BOARD THICKNESS
(1.4 ± .2) / .055 ± .008
- 5) THIS MARK INDICATES CIRCUIT NO.1.
- 6) FOR (0.635) / .025 SQ. MALE PINS THE LENGTH MUST BE (5.65) / .222 MIN & (7.00) / .276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.

DETAIL "A"



TERMINAL RETENTION FEATURE

SHT385, UPDATE SEC C-C			QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
					MM ONLY		NTS	METRIC	
DESCRIPTION					DRAWN BY DATE		TITLE		
					1987/07/14				
					CHECKED BY DATE				
			1987/07/14						
REV			APPROVED BY DATE		MOLEX MOLEX INCORPORATED				
			2010/01/14						
C			MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			SEE TABLE		SDA-90152		3 OF 5		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

	10		9		8		7		6		5		4		3		2		1	
F	PART NO.	CKT	DIM. A		DIM. B (+0.00 -0.30 +0.00 -0.12)		PCS/ TUBE	PLATING VERSION A PRE-PLATED HOT DIP TIN 1.0 TO 2.5 microns (.00004" TO .00010"). PLATING VERSION E 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL). PLATING VERSION F. 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL). PLATING VERSION G. 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												
	90152-XX04	4	(2.54)	.100	(5.08)	.200	109													
	06	6	(5.08)	.200	(7.62)	.300	73													
	08	8	(7.62)	.300	(10.16)	.400	55													
	10	10	(10.16)	.400	(12.70)	.500	44													
	12	12	(12.70)	.500	(15.24)	.600	36													
	14	14	(15.24)	.600	(17.78)	.700	31													
	16	16	(17.78)	.700	(20.32)	.800	27													
	18	18	(20.32)	.800	(22.86)	.900	24													
	20	20	(22.86)	.900	(25.40)	1.000	22													
E	22	22					20													
	24	24	(27.94)	1.100	(30.48)	1.200	18													
	26	26	(30.48)	1.200	(33.02)	1.300	16													
	28	28					14													
D	30	30	(35.56)	1.400	(38.10)	1.500	14													
	32	32					13													
	34	34	(40.64)	1.600	(43.18)	1.700	12													
	36	36	(43.18)	1.700	(45.72)	1.800	12													
	38	38	(45.72)	1.800	(48.26)	1.900	11													
	40	40	(48.26)	1.900	(50.80)	2.000	11													
	42	42					10													
	44	44	(53.34)	2.100	(55.88)	2.200	10													
	46	46					10													
	48	48					9													
C	50	50	(60.96)	2.400	(63.50)	2.500	8													
	52	52					8													
	54	54					8													
	56	56	(68.58)	2.700	(71.12)	2.800	7													
	58	58					7													
	60	60	(73.66)	2.900	(76.20)	3.000	7													
B	62	62					6													
	90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5													
A								90152-XXYY INDICATES NO. OF CIRCUITS. PLATING CODE. 31 = VERSION A. 32 = VERSION E. 33 = VERSION F. 35 = VERSION G.												
tb_frame_A3_P_AM_T Rev. F 2009/06/18		9	8	7	6	5	4	3	2	1										

